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(71) Applicant: **FUJIFILM ELECTRONIC MATERIALS U.S.A., INC.** [US/US]; 80 Circuit Drive, N. Kingstown, Rhode Island 02852 (US).

(72) Inventors: **SCHAEFER, Zachary L.**; 9436 East Emelita Avenue, Mesa, Arizona 85208 (US). **TURNER, Eric**; 1901 W Madison Street, Apt. #846, Phoenix, Arizona 85009 (US). **BALLESTEROS, Carl**; 25 W Dexter Way, San Tan Valley, Arizona 85143 (US).

(74) Agent: **ZHANG, Tony**; Fish & Richardson P.C., P.O. Box 1022, New York, New York 55440-1022 (US).

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(54) Title: POLISHING COMPOSITIONS AND METHODS OF USING THE SAME

(57) Abstract: This disclosure relates to a polishing composition that includes at least one abrasive; at least one pH adjuster, and at least one biosurfactant, as well as a method of using the polishing composition to polish a substrate. The biosurfactant can be selected from the group consisting of glycolipids, lipopeptides, and mixtures thereof.



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